PCN Number:	20150323001		PC	N Date:	03/25/2015	
Title: Datasheet update for TPS57160-Q1						
Customer Contact:	PCN Manager		Dept:	Quality Service		y Services
Change Type:						
Assembly Site	[Design			/afer Bun	
Assembly Process		🛛 Data Sheet		Wafer Bump Material		
Assembly Materials		Part number of	change	Wafer Bump Process		
Mechanical Specification		Test Site			Wafer Fab Site Wafer Fab Materials	
Packing/Shipping/	Labeling	Test Process		=		
PCN Details				Process		
Description of Change:						
Texas Instruments Incorporated is announcing an information only notification.						
The product datasheet	(s) is being up	dated as summa	rized below.			
The following change h	vistory provido	s furthor dotails				
The following change history provides further details.						
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TPS57160-Q1					• 11	STRUMENTS
SLVSAP1E – DECEMBER 2010 – REVISED MARCH 2015 www.ti.com						
SLVSAP1E-DECEMBER 2010-REV	ISED MARCH 2015					www.u.com
SLVSAP1E - DECEMBER 2010 - REVI Changes from Revision D (F		Revision E				Page
Changes from Revision D (F	ebruary 2015) to F					Page
	ebruary 2015) to F	SD rating				Page
Changes from Revision D (F • Updated the corner pin val	ebruary 2015) to F lues for the CDM Es mation values for th	SD rating e DGQ (MSOP) and D	RC (VSON) packag	es in t	he Thermal	Page 4
 Changes from Revision D (F Updated the corner pin val Changed the thermal information table 	ebruary 2015) to F lues for the CDM Es mation values for th	SD rating e DGQ (MSOP) and D	RC (VSON) packag	es in t	he Thermal	Page 4
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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